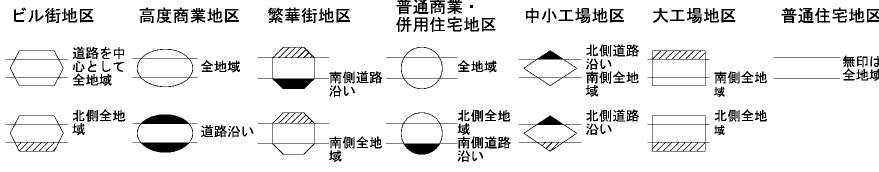
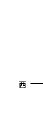


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記号	借地権割合	記号	借地権割合
A	90%	E	50%
B	80%	F	40%
C	70%	G	30%
D	60%		



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37071 当図 37073

世田谷区  
(世田谷署)

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